PCF21xxC family

LCD drivers

Rev. 3 — 6 May 2015 Product data sheet

1. General description

The PCF21xxC family are single-chip, silicon gate CMOS LCD driver circuits. A 3-line bus (C-bus) structure enables serial data transfer with microcontrollers.

2. Features and benefits

- Supply voltage 2.25 V to 6.0 V
- Low current consumption
- Serial data input
- C-bus control
- One-point built-in oscillator
- Stand-alone or expanded system
- Power-on reset clear
- LCD segments: 40 (PCF2100C), 64 (PCF2111C) and 32 (PCF2112C)
- Multiplex rate: 1:2 (PCF2100C and PCF2111C) and 1:1 (PCF2112C)
- Word length: 22 bits (PCF2100C) and 34 bits (PCF2111C and PCF2112C)

3. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
PCF2100CT	SO28	plastic small outline package; 28 leads; body width 7.5 mm	SOT136-1
PCF2111CT	VSO40	plastic very small outline package; 40 leads	SOT158-1
PCF2112CT	VSO40	plastic very small outline package; 40 leads	SOT158-1

3.1 Ordering options

Table 2. Ordering options

Product type number	Orderable part number	Sales item (12NC)	Delivery form	IC revision
PCF2100CT/F1	PCF2100CT/F1,112	935195690112	tube	1
	PCF2100CT/F1,118	935195690118	tape and reel, 13 inch	1
PCF2111CT/1	PCF2111CT/1,112	935278772112	tube	1
	PCF2111CT/1,118	935278772118	tape and reel, 13 inch	1
PCF2112CT/1	PCF2112CT/1,112	935279199112	tube	1
	PCF2112CT/1,118	935279199118	tape and reel, 13 inch	1

4. Marking

Table 3. Marking codes

Type number	Marking code
PCF2100CT	PCF2100CT
PCF2111CT	PCF2111CT
PCF2112CT	PCF2112CT

5. Block diagram

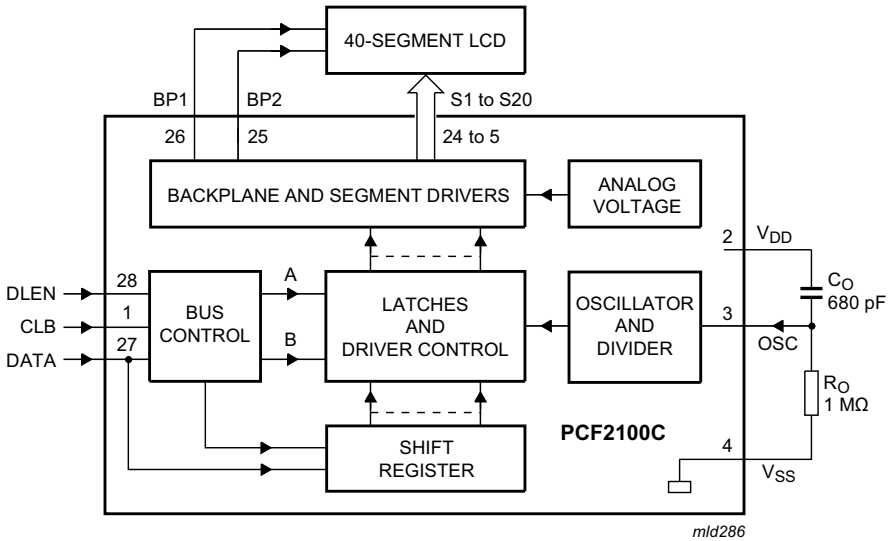


Fig 1. Block diagram; PCF2100C

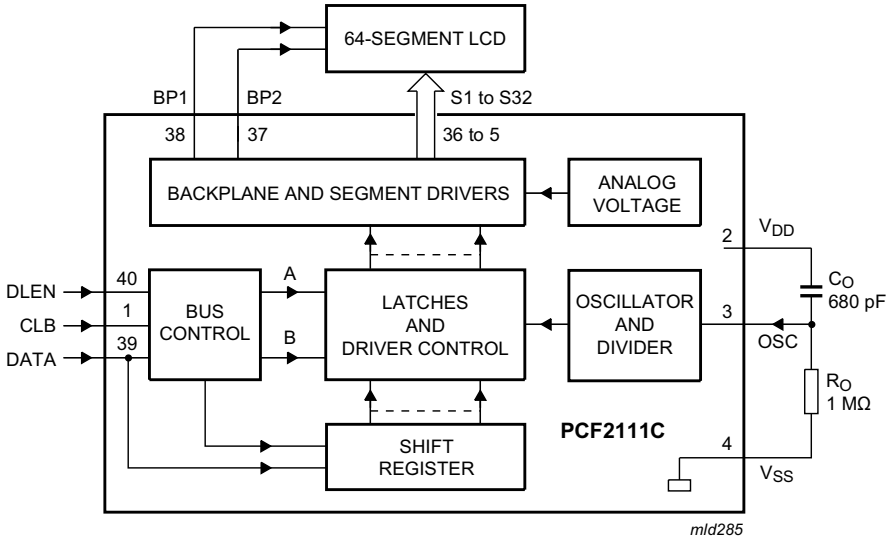


Fig 2. Block diagram; PCF2111C

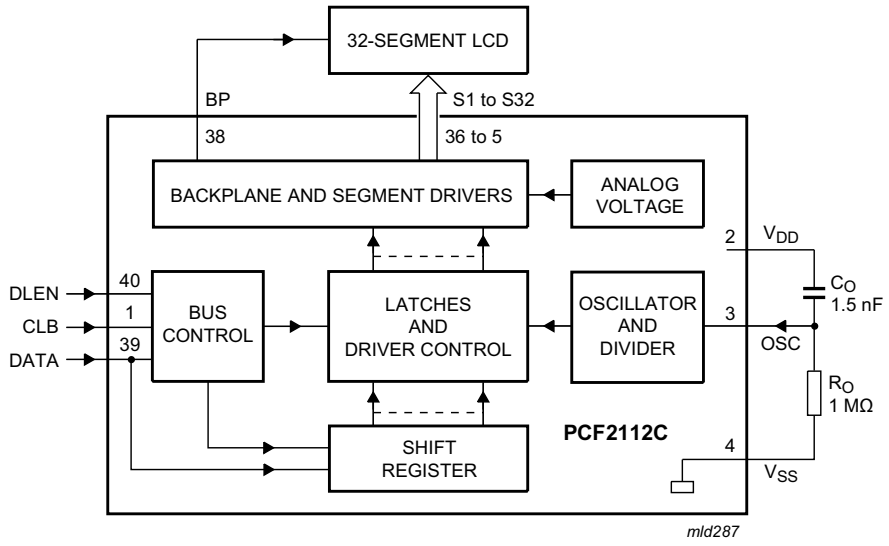


Fig 3. Block diagram; PCF2112C

6. Pinning information

6.1 Pinning

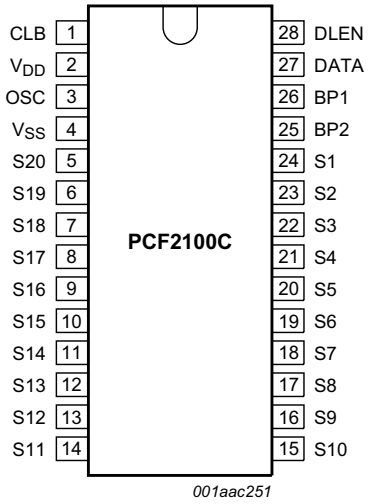


Fig 4. Pin configuration PCF2100C (SOT136-1)

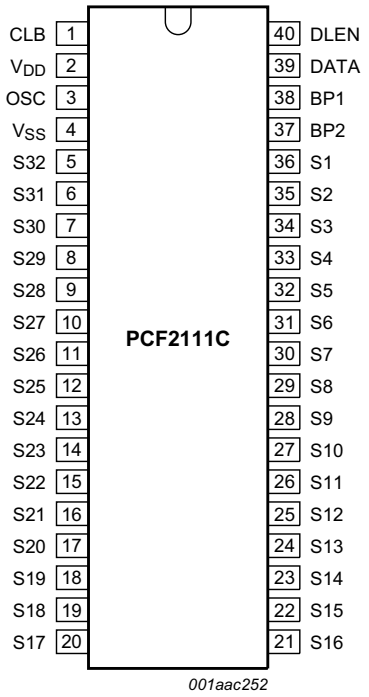


Fig 5. Pin configuration PCF211C (SOT158-1)

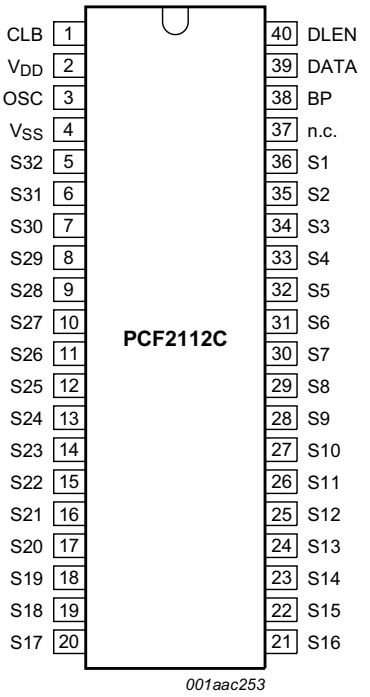


Fig 6. Pin configuration PCF2112C (SOT158-1)

6.2 Pin description

Table 4. Pin description

Input or input/output pins must always be at a defined level (V_{SS} or V_{DD}) unless otherwise specified.

Symbol	Pin			Description
	PCF2100C	PCF2111C	PCF2112C	
CLB	1	1	1	clock burst input (C-bus)
V_{DD}	2	2	2	supply voltage
OSC	3	3	3	oscillator input
V_{SS}	4	4	4	supply voltage ground
S32	-	5	5	LCD driver output
S31	-	6	6	
S30	-	7	7	
S29	-	8	8	
S28	-	9	9	
S27	-	10	10	
S26	-	11	11	
S25	-	12	12	

Table 4. Pin description *...continued*

Input or input/output pins must always be at a defined level (V_{SS} or V_{DD}) unless otherwise specified.

Symbol	Pin			Description
	PCF2100C	PCF2111C	PCF2112C	
S24	-	13	13	LCD driver output
S23	-	14	14	
S22	-	15	15	
S21	-	16	16	
S20	5	17	17	
S19	6	18	18	
S18	7	19	19	
S17	8	20	20	
S16	9	21	21	
S15	10	22	22	
S14	11	23	23	
S13	12	24	24	
S12	13	25	25	
S11	14	26	26	
S10	15	27	27	
S9	16	28	28	
S8	17	29	29	
S7	18	30	30	
S6	19	31	31	
S5	20	32	32	
S4	21	33	33	
S3	22	34	34	
S2	23	35	35	
S1	24	36	36	
BP2	25	37	-	backplane driver output 2
n.c.	-	-	37	not connected
BP1	26	38	-	backplane driver output 1
BP	-	-	38	backplane driver output
DATA	27	39	39	data input line (C-bus)
DLEN	28	40	40	data input line enable (C-bus)

7. Functional description

An LCD segment or LED output is activated when the corresponding DATA bit is HIGH; see Figure 7.

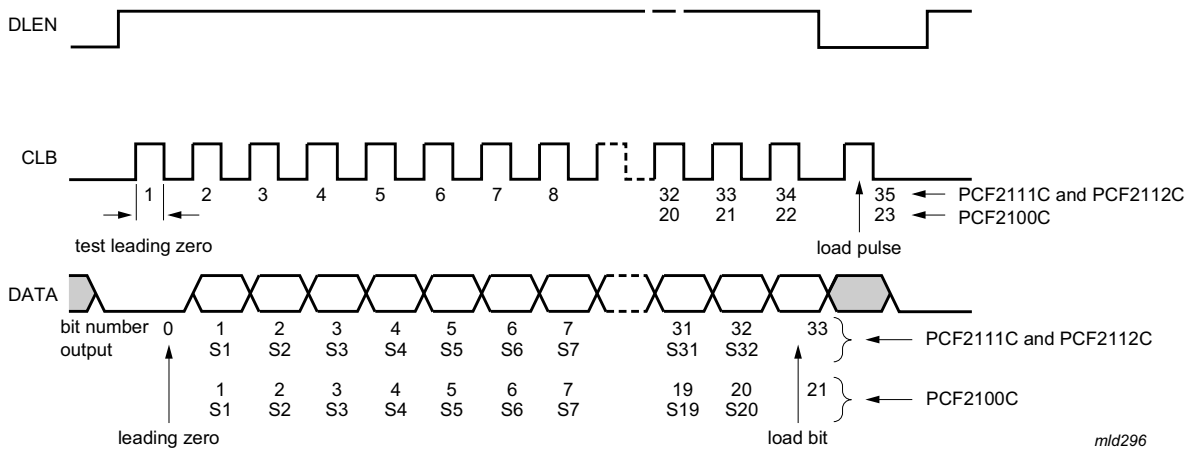


Fig 7. C-bus data format

7.1 PCF2100C

When DATA bit 21 is HIGH, the A-latches (BP1) are loaded. With DATA bit 21 LOW, the B-latches (BP2) are loaded. CLB pulse 23 transfers data from the shift register to the selected latches.

7.2 PCF2111C

When DATA bit 33 is a HIGH, the A-latches (BP1) are loaded. With DATA bit 33 LOW, the B-latches (BP2) are loaded. CLB pulse 35 transfers data from the shift register to the selected latches.

7.3 PCF2112C

When DATA bit 33 is HIGH, the latches are loaded. CLB pulse 35 transfers data from the shift register to the selected latches.

7.4 Bus control logic

The following tests are carried out by the bus control logic:

1. Test on leading zero
2. Test on number of DATA bits
3. Test of disturbed DLEN and DATA signals during transmission

If one of the test conditions is not fulfilled, no action follows the load condition (load pulse with DLEN LOW) and the driver is ready to receive new data.

7.5 Timing

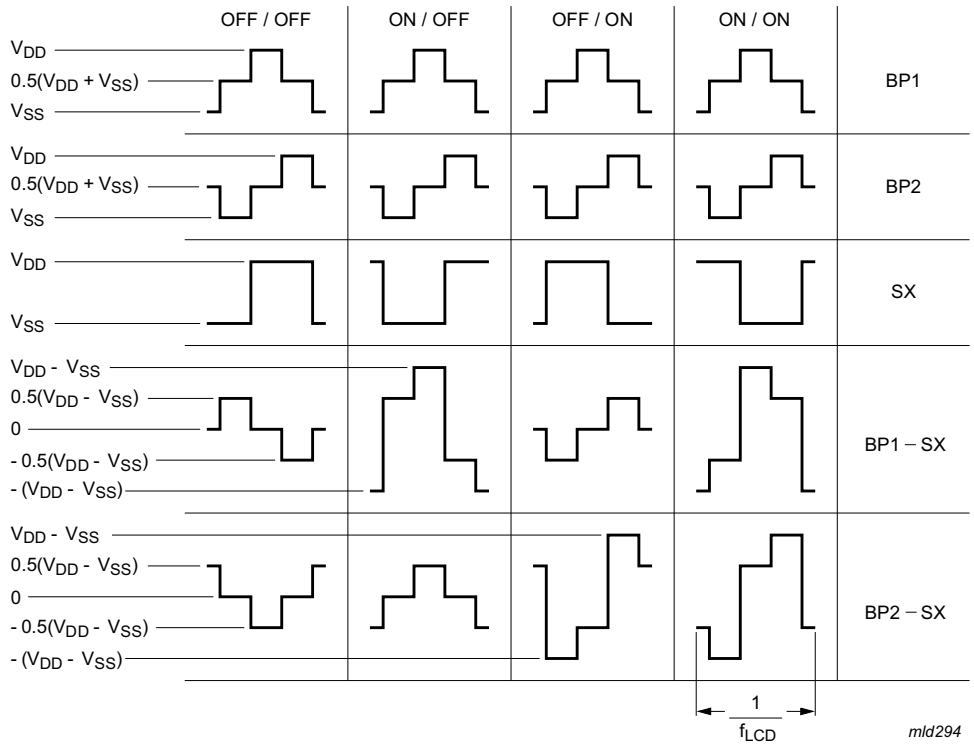


Fig 8. Timing diagram for PCF2100C and PCF2111C

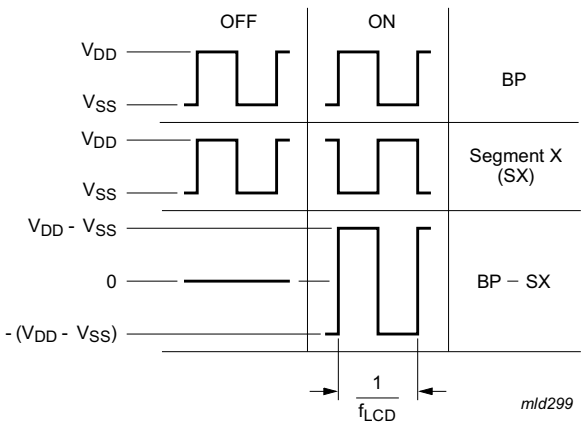
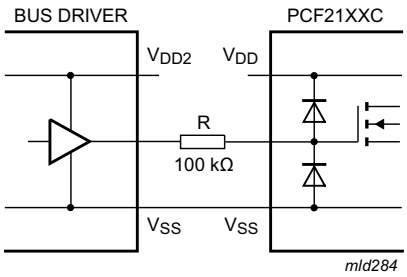


Fig 9. Timing diagram for PCF2112C

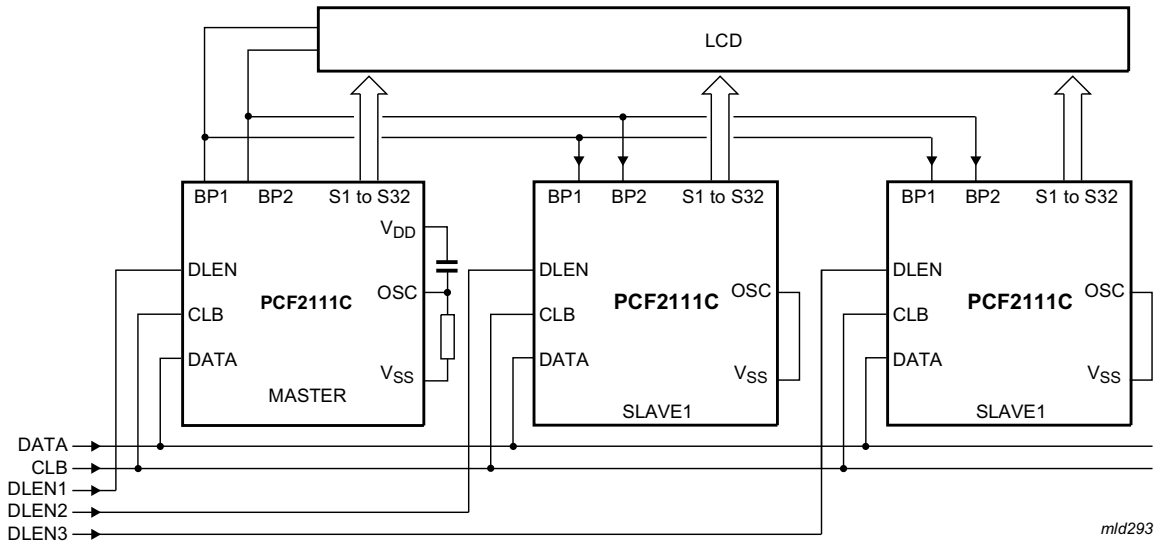
7.6 Input circuitry



V_{SS} line is common. In systems where it is expected that $V_{DD2} > V_{DD1} + 0.5$ V, a resistor should be inserted to reduce the current flowing through the input protection. Maximum input current ≤ 40 μA.

Fig 10. Input circuitry

7.7 Expansion



By connecting OSC to V_{SS} the BP pins become inputs and generate signals synchronized to the single oscillator frequency, thus allowing expansion of several members of the PCF21xxC family up to the BP drive capability of the master. The PCF2112C can only function as a master for other PCF2112Cs.

Fig 11. Expansion possibility (using PCF2111C)

8. Safety notes

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

CAUTION

Static voltages across the liquid crystal display can build up when the LCD supply voltage (V_{LCD}) is on while the IC supply voltage (V_{DD}) is off, or vice versa. This may cause unwanted display artifacts. To avoid such artifacts, V_{LCD} and V_{DD} must be applied or removed together.

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		−0.5	+8.0	V
V_I	input voltage	on pins DLEN, CLB, DATA and OSC	V_{SS} − 0.5	V_{DD} + 0.5	V
V_O	output voltage	on pins BP1, BP2 and S1 to S32	V_{SS} − 0.5	V_{DD} + 0.5	V
I_{DD}	supply current		−50	+50	mA
I_{SS}	ground supply current		−50	+50	mA
I_I	input current		−20	+20	mA
I_O	output current		−25	+25	mA
P_{tot}	total power dissipation	[1]	-	500	mW
P/out	power dissipation per output		-	100	mW
V_{ESD}	electrostatic discharge voltage	HBM [2]	-	±2000	V
I_{lu}	latch-up current	[3]	-	100	mA
T_{amb}	ambient temperature	operating device	−40	+85	°C
T_{stg}	storage temperature	[4]	−65	+150	°C

[1] Derate by 7.7 mW/K when T_{amb} > 60 °C.

[2] Pass level; Human Body Model (HBM), according to Ref. 7 “JESD22-A114”.

[3] Pass level; latch-up testing according to Ref. 8 “JESD78” at maximum ambient temperature ($T_{amb(max)}$).

[4] According to the store and transport requirements (see Ref. 13 “UM10569”) the devices have to be stored at a temperature of +8 °C to +45 °C and a humidity of 25 % to 75 %.

10. Static characteristics

Table 6. Static characteristics

V_{DD} = 2.25 V to 6.0 V; V_{SS} = 0 V; T_{amb} = −40 °C to +80 °C; R_O = 1 MΩ; C_O = 680 pF; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply						
V_{DD}	supply voltage		2.25	-	6.0	V
I_{DD}	supply current	[1]	-	20	50	μA
		T_{amb} = 25 °C [1]	-	20	30	μA
V_{POR}	power-on reset voltage	[2]	-	1.0	1.6	V
Inputs CLB, DATA and DLEN						
V_{IL}	LOW-level input voltage		-	-	0.8	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
I_{LI}	input leakage current	V_I = V_{SS} or V_{DD}	-	-	±1	μA
C_i	input capacitance	[3]	-	-	10	pF
Input OSC						
I_{osc}	oscillator start-up current	V_I = V_{SS}	0.5	1.2	5.0	μA
LCD outputs						
V_{BP}	voltage on pin BP		-	±20	-	mV
$Z_{O(BP)}$	backplane driver output impedance	V_{DD} = 5 V [4]	-	0.5	5.0	kΩ
$Z_{O(S)}$	segment driver output impedance	V_{DD} = 5 V [4]	-	1	7	kΩ

[1] Outputs open; C-bus inactive; see Figure 13.

[2] Resets all logic, when V_{DD} < V_{POR}.

[3] Periodically sampled (not 100 % tested).

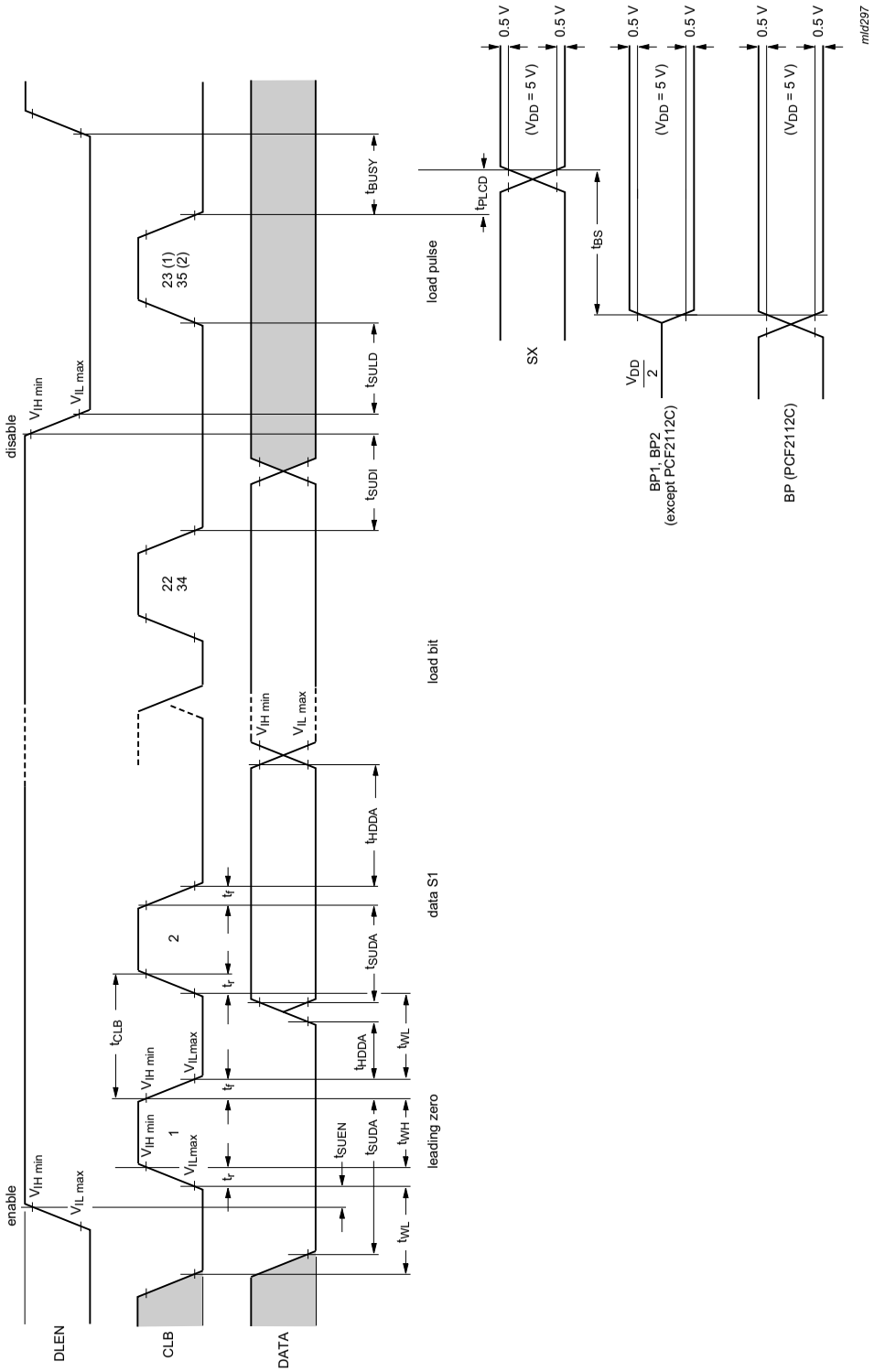
[4] Outputs measured one at a time.

11. Dynamic characteristics

Table 7. Dynamic characteristics

V_{DD} = 2.25 V to 6.0 V; V_{SS} = 0 V; T_{amb} = −40 °C to +80 °C; R_O = 1 MΩ; C_O = 680 pF; all timing values are referenced to V_{IH} and V_{IL} levels with an input voltage swing of V_{SS} to V_{DD}; unless otherwise specified.

Symbols	Parameter	Conditions	Min	Typ	Max	Unit
Inputs CLB, DATA and DLEN; see Figure 12						
t_{SUDA}	data setup time		3	-	-	µs
t_{HDDA}	data hold time		3	-	-	µs
t_{SUEN}	enable setup time		1	-	-	µs
t_{SUDI}	disable setup time		2	-	-	µs
t_{SULD}	load pulse setup time		2.5	-	-	µs
t_{BUSY}	busy time		3	-	-	µs
t_{WH}	CLB HIGH time		1	-	-	µs
t_{WL}	CLB LOW time		5	-	-	µs
t_{CLB}	CLB cycle time		10	-	-	µs
t_r	rise time		-	-	10	µs
t_f	fall time		-	-	10	µs
LCD timing; see Figure 12 to Figure 17						
f_{LCD}		PCF2100C, PCF2111C	60	75	100	Hz
		PCF2112C; C_O = 1.5 nF	30	35	50	Hz
t_{BS}	transfer time	with test loads; V_{DD} = 5 V	-	20	100	µs
t_{PLCD}	driver delay time	with test loads; V_{DD} = 5 V	-	20	100	µs



(1) Load pulse 23 for PCF2100C; see Figure 7.

(2) Load pulse 35 for PCF2111C and PCF2112C; see Figure 7.

Fig 12. C-bus timing

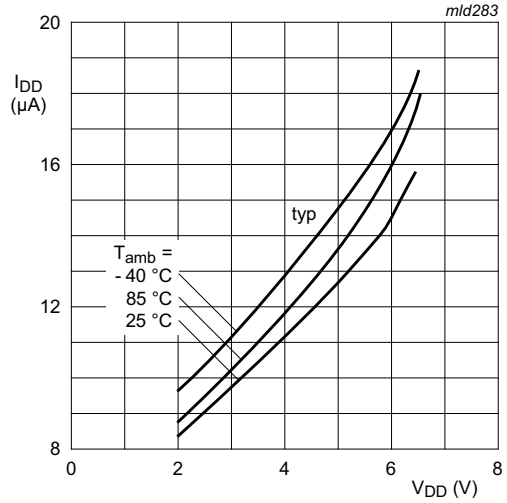


Fig 13. Supply current as a function of supply voltage

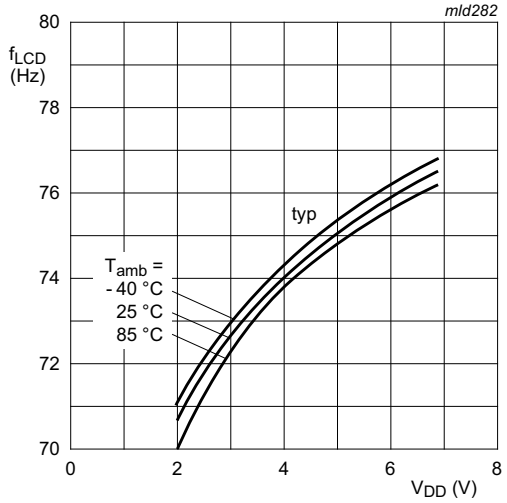


Fig 14. Display frequency as a function of supply voltage; C_O = 680 pF (except PCF2112C)

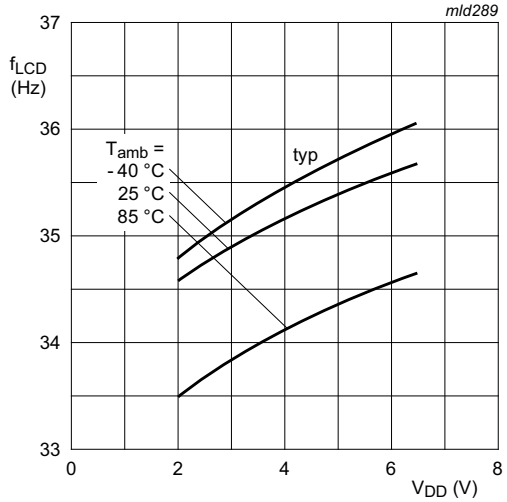


Fig 15. Display frequency as a function of supply voltage; C_O = 1.5 nF (only PCF2112C)

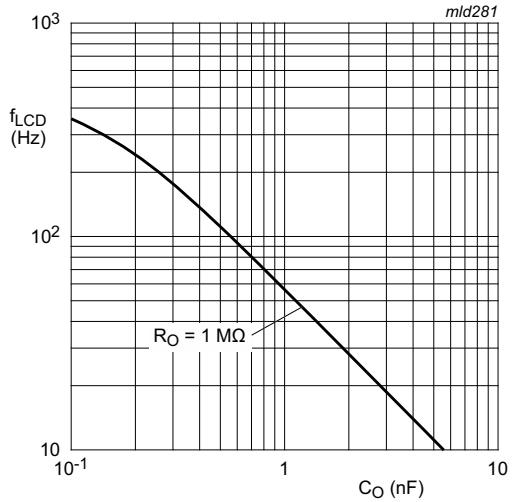


Fig 16. Display frequency as a function of R_O and C_O; T_{amb} = 25 °C; V_{DD} = 5 V

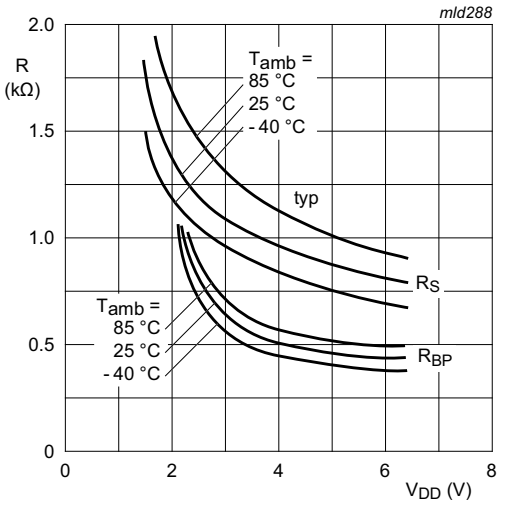


Fig 17. Output resistance of backplane and segments as a function of supply voltage

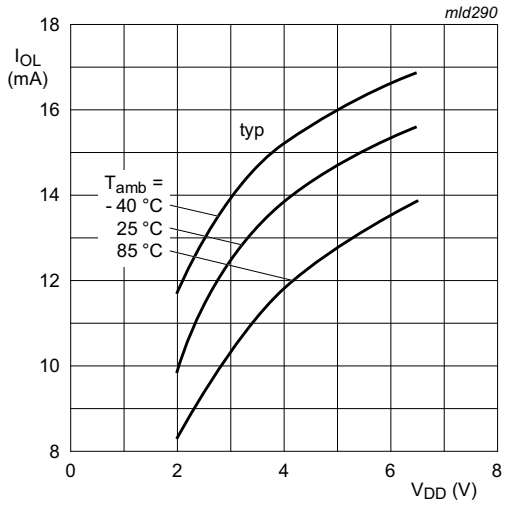
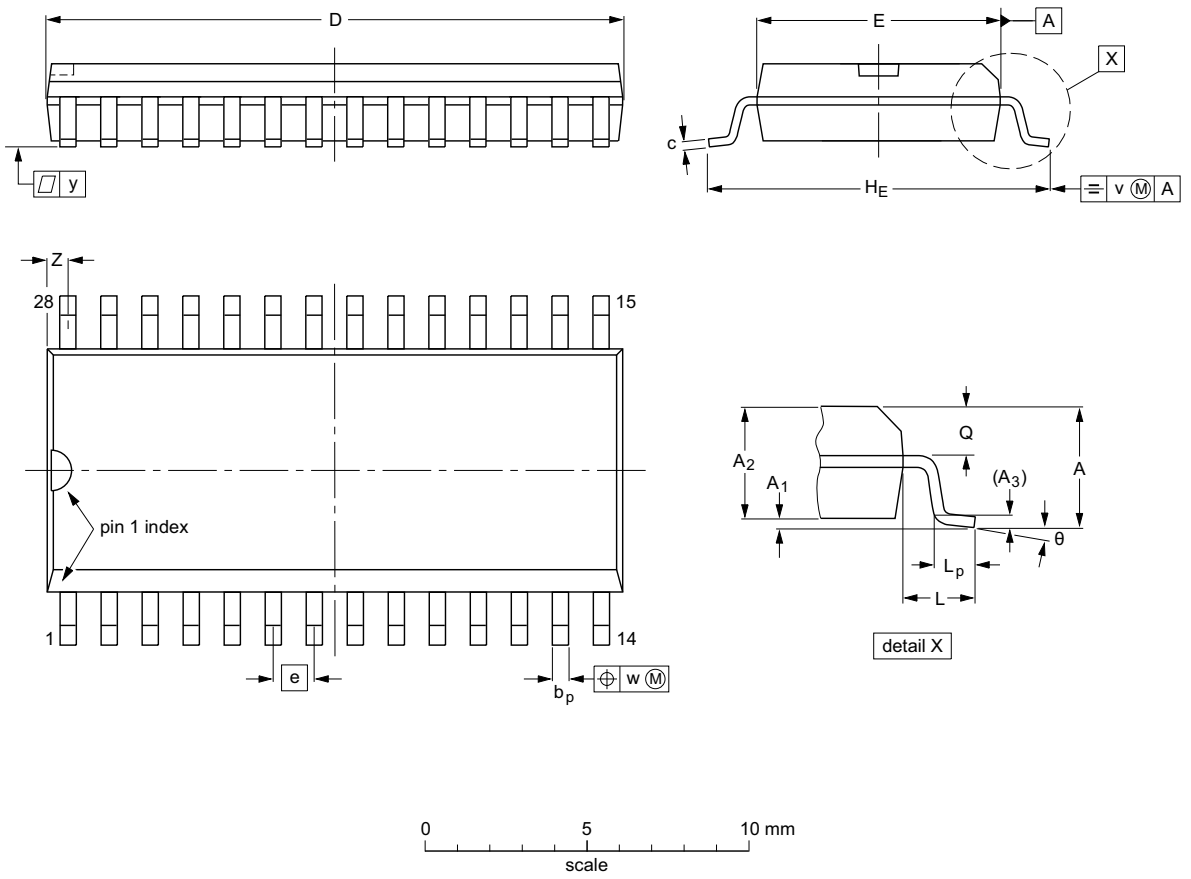


Fig 18. LOW-level output current as a function of supply voltage (only PCF2112C)

12. Package outline

SO28: plastic small outline package; 28 leads; body width 7.5 mm **SOT136-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	18.1 17.7	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.71 0.69	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

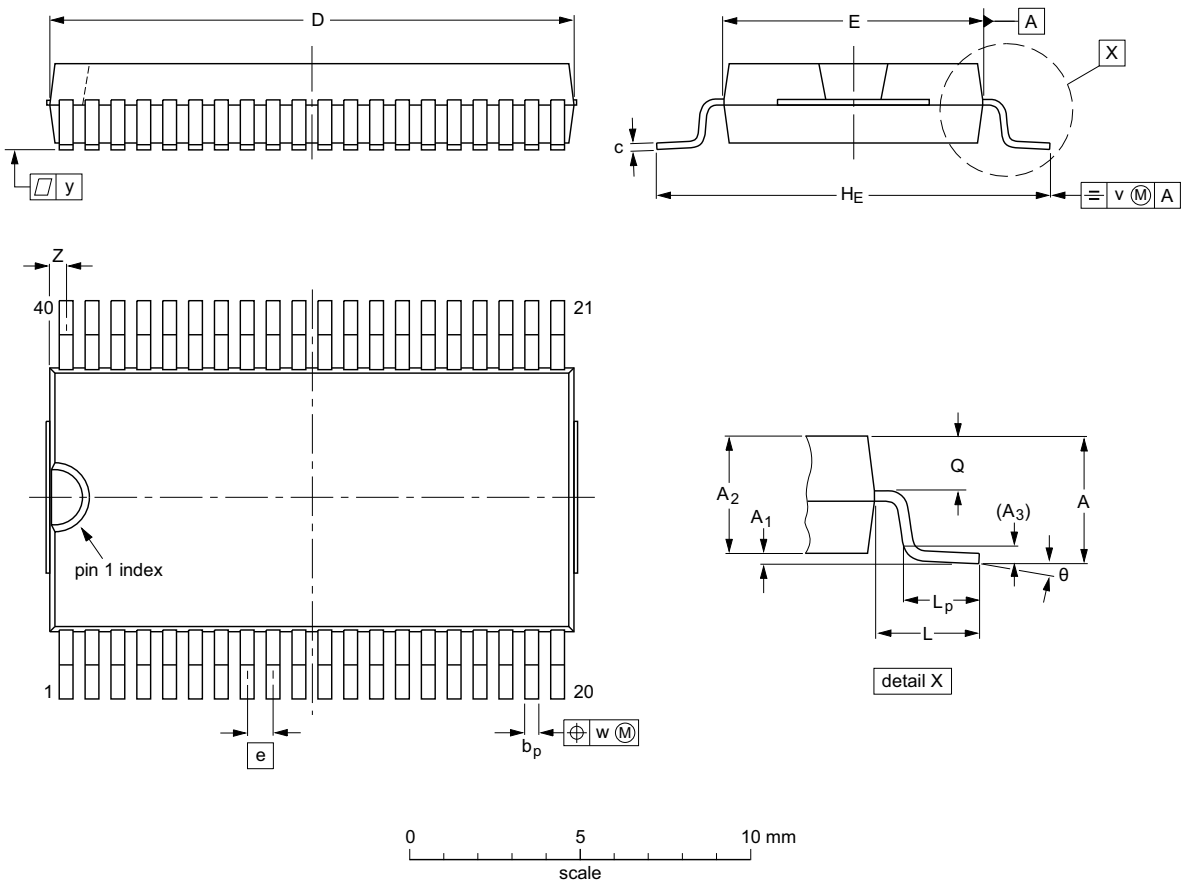
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT136-1	075E06	MS-013				~~99-12-27~~ 03-02-19

Fig 19. Package outline SOT136-1 (SO28)

VSO40: plastic very small outline package; 40 leads **SOT158-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.7	0.3 0.1	2.45 2.25	0.25	0.42 0.30	0.22 0.14	15.6 15.2	7.6 7.5	0.762	12.3 11.8	2.25	1.7 1.5	1.15 1.05	0.2	0.1	0.1	0.6 0.3	7° 0°
inches	0.11	0.012 0.004	0.096 0.089	0.01	0.017 0.012	0.0087 0.0055	0.61 0.60	0.30 0.29	0.03	0.48 0.46	0.089	0.067 0.059	0.045 0.041	0.008	0.004	0.004	0.024 0.012	

Notes

1. Plastic or metal protrusions of 0.4 mm (0.016 inch) maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT158-1						~~95-01-24~~ 03-02-19

Fig 20. Package outline SOT158-1 (VSO40)

13. Handling information

All input and output pins meet the requirements of the *MIL-STD-883 class 2*, method 3015 ElectroStatic Discharge (ESD) test. When handling Metal-Oxide Semiconductor (MOS) devices ensure that all normal precautions are taken as described in *JESD625-A*, *IEC 61340-5* or equivalent standards.

14. Packing information

14.1 Tape and reel information

For tape and reel packing information, see Ref. 10 “SOT136-1_118” and Ref. 11 “SOT158-1_118”.

15. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 “Surface mount reflow soldering description”*.

15.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

15.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation

- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

15.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

15.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 21) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 8 and 9

Table 8. SnPb eutectic process (from J-STD-020D)

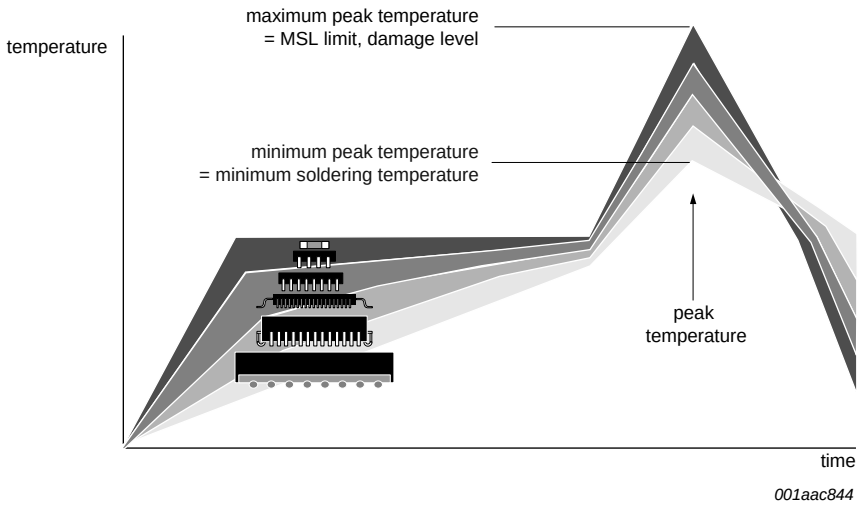
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm^3)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 9. Lead-free process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm^3)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 21.



MSL: Moisture Sensitivity Level

Fig 21. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

16. References

[1] **AN10365 —** Surface mount reflow soldering description

[2] **AN10853 —** ESD and EMC sensitivity of IC

[3] **AN11267 —** EMC and system level ESD design guidelines for LCD drivers

[4] **IEC 60134 —** Rating systems for electronic tubes and valves and analogous semiconductor devices

[5] **IEC 61340-5 —** Protection of electronic devices from electrostatic phenomena

[6] **IPC/JEDEC J-STD-020D —** Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices

[7] **JESD22-A114 —** Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)

[8] **JESD78 —** IC Latch-Up Test

[9] **JESD625-A —** Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices

[10] **SOT136-1_118 —** SO28; Reel dry pack; SMD, 13", packing information

[11] **SOT158-1_118 —** VSO40; Reel pack; SMD, 13", packing information

[12] **UM10204 —** I^2C-bus specification and user manual

[13] **UM10569 —** Store and transport requirements

17. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF21XXC_FAM v.3	20150506	Product data sheet	-	PCF21XXC_FAMILY v.2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Changed Figure 16.			
PCF21XXC_FAMILY v.2	19970328	Product specification	-	PCF21XXC_FAMILY v.1
PCF21XXC_FAMILY v.1	19950503	-	-	-

18. Legal information

18.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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20. Tables

21. Figures

22. Contents

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